50th International Spring Seminar on Electronics Technology

DRESDEN, GERMANY



1st Call for Papers

ISSE 2027 CONFERENCE

MAY,12-16 2027

"Semiconductor Packaging Technologies for a Resilient European Industry"

Distinguished Colleagues, Dear Researchers and Scientists,

we are delighted to invite you to submit an extended abstract to the **anniversary 50th edition of the International Spring Seminar on Electronics Technology (ISSE)** from May 12th to May 16th, 2027, organized in Dresden, Germany.

The International Spring Seminar on Electronics Technology (ISSE) is the premier European forum for exchanging information between senior and young scientists from academic communities and electronic industries around the world. Topics include experimental and theoretical work in a widespread field of electronics and micro/nanoelectronics technology, electronics manufacturing, electronics packaging, advanced research, and teaching. Based on a combination of oral and poster presentations as well as individual meetings, professors, industrial participants, students, senior and junior researchers come together in a unique forum to discuss scientific and educational topics and organize international cooperation in a convenient atmosphere during the conference days. ISSE 2027 will continue the long tradition of the preceding ISSE conferences, starting in 1977 (Weissig/Germany) and the last one held in Plovdiv (Bulgaria, 2026).

We are pleased to encourage you to participate in **ISSE 2027**.

IEEE

IEEE ELECTRONICS PACKAGING SOCIETY

Technische Universität Dresden

AVT

Check our website for details and updates
https://isse-conf.eu/

Submit your abstract!

https://cmt3.research.microsoft.com/ISSE2027

DRESDEN GERMANY

50th IEEE International Spring Seminar on Electronics Technology

Important Dates

Abstract submission:	**January 10th, 2027**
Notification of acceptance:	**March 1st, 2027**
Early bird registration:	**March 8th, 2027**
Full paper submission:	**April 4th, 2027**

Conference Topics

A. New Materials, Components and Processes
B. Thermal Management
C. Advanced Packaging and Interconnection Technologies
D. Testing, Reliability and Quality Management
E. Process, Multiphysics, Thermal and Mechanical Simulation
F. Sustainability in Electronics Technology
G. Nanotechnology, Nanomaterials and Nanoelectronic
H. Circuit Design, Signal and Power Integrity, Electromagnetic Compatibility
I. Electronic components, Sensors, Actuators and Microsystems
J. Educational and Information Technologies in Electronics Manufacturing

Publication of Papers

accepted and presented papers will be featured in the conference proceedings and will be sent to the IEEE Xplore Digital Library (ieeexplore.ieee.org) subject to meeting IEEE Xplore's scope and quality requirements. Plagiarism checks will be conducted on all submissions. It is essential that the papers are original, have not been previously published, and refrain from including commercial content. We are pleased to inform you that selected articles presented at the ISSE 2027 conference will have the opportunity to be published in a peer-reviewed journal IEEE Transactions on Components, Packaging and Manufacturing Technology (TCPMT) and in a special issue of Power Electronic Devices and Components Journal (PEDC).

Conference Venue

ISSE 2027 will take place at the Taste Hotel Dresden





ISSE 2027 Conference Organizers

General Chair:	**Olivér Krammer (BME, Hungary)**
Conference Chair:	**Juliana Panchenko (TUD, Germany)**
Secretary of ISSE:	**David Bušek (CTU, Czech Republic)**
Technical Program Chair:	**Tomáš Blecha (UWB, Czech Republic)**
Publication Chair:	**Bogdan Mihăilescu (UPB, Romania)**

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